

RELIABILITY MONITOR

STRESS: WRITE CYCLE STRESS

CONDITIONS: 85 C, 7.0 VOLTS

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1620	D1	MAR '01	26780	0106	CPS (ChipPac, China)	DH045040AA	SOIC	50	50	0
DS1620	D1	JUN '01	27096	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	50	50	0
DS1620	D1	SEP '01	27862	0111	NSEB	DJ051232AAI	SOIC	50	50	0
DS1620	D1	DEC '01	28596	0112	CPS (ChipPac, China)	DH052443AAD	SOIC	50	50	0

RELIABILITY MONITOR

STRESS: VAPOR PHASE REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS5002	C5	JAN '01	26506	0047 ATK (Amkor, K)	DN028766AAD	MQFP	3	203	0
DS5002	C5	APR '01	26899	0112 ATK (Amkor, K)	DN030363AAA	MQFP	3	203	0

RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1232	C2-L	APR '01	26861	0105	OSEP	DE045054ABB	SOIC	4	0
DS1233	A5	APR '01	26868	0101	Fastech	DA048537AF	SOT223	4	0
DS1233	A5	JUL '01	27349	0110	Carsem	DM048543AA	SOT223	4	0
DS1233	A5	OCT '01	28003	0128	Fastech	DA102602AC	SOT223	4	0
DS1267	A1	MAY '01	26976	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	4	0
DS1620	D1	MAR '01	26773	0106	CPS (ChipPac, China)	DH045040AA	SOIC	4	0
DS1620	D1	JUN '01	27090	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	4	0
DS1620	D1	SEP '01	27856	0111	NSEB	DJ051232AAI	SOIC	4	0
DS1803	A2	FEB '01	26606	0105	OSEP	DE047362AAB	SOIC	4	0
DS1803	A2	MAY '01	26990	0115	Carsem	DM052456AC	SOIC	4	0
DS1803	A2	AUG '01	27560	0119	OSEP	DE105519ACA	SOIC	4	0
DS2108	B7	AUG '00	25854	0029	ATP (Amkor, PI)	DK016058AA	SOIC	4	0
DS2118M	B1	SEP '01	27871	0124	Carsem	DM106644AA	SSOP	4	0
DS21352	A4	JUN '01	27343	0103	ATP (Amkor, PI)	DN033071AAA	LQFP	4	0
DS2154	A2	JUN '01	27098	0107	Stats	DC040702AA-	LQFP	4	0
DS2154	A2	SEP '01	27838	0125	ATK (Amkor, K)	DN104641AA-	LQFP	4	0
DS2154	A2	DEC '01	28580	0126	ATP (Amkor, PI)	DK119150AAA	LQFP	4	0
DS2175	D1	APR '01	26880	0050	ATP (Amkor, PI)	DK036683AB	SOIC	4	0
DS21Q43	A3-A	SEP '01	27877	0047	Stats	DC036714AAD	LQFP	4	0
DS21S07	C1-	FEB '01	26584	0047	Carsem	DM035532AF	TSSOP	4	0
DS2502	C4	APR '01	26914	0107	OSEP	DE041143AKA	TSOC	4	0
DS2502	C4	JUL '01	27372	0125	OSEP	DE052527ACA	TSOC	4	0

RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS5002	C5	JAN '01	26505	0047 ATK (Amkor, K)	DN028766AAD	MQFP	4 0
DS5002	C5	APR '01	26898	0112 ATK (Amkor, K)	DN030363AAA	MQFP	4 0
DS80CH11	A4	MAR '01	26782	0103 ATK (Amkor, K)	DN029182AAA	LQFP	4 0
DS80CH11	A4	JUN '01	27104	0108 ATK (Amkor, K)	DN034351AA	LQFP	4 0
DS80CH11	A4	SEP '01	27864	0110 Stats	DC037148AA	LQFP	4 0
DS80CH11	A4	DEC '01	28598	0113 ATK (Amkor, K)	DN036754AA	LQFP	4 0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -40 TO 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JUL '01	27334	0119	Fastech	302244	Module w/SMT	300	99	1
DS1230	A1-Y	JAN '02	28621	0201	Fastech	304930	Module w/SMT	300	100	2
DS12887	A2-	JAN '01	26451	0043	Fastech	300511	Module w/Bent Fra	300	100	0
DS12887	A2-	APR '01	26878	0102	Fastech	301097	Module w/Bent Fra	300	100	0
DS12887	A2-	JUL '01	27359	0121	Fastech	302296	Module w/Bent Fra	300	100	0
DS12887	A2-	OCT '01	28013	0137	Fastech	303363	Module w/Bent Fra	300	100	0
DS12887	A2-	JAN '02	28607	0203	Dallas	305911	Module w/Bent Fra	300	100	0
DS1644	B2	& DS9034	26628	0051	Fastech	300700	Power Cap	300	77	0
DS1992	E7-F	SEP '01	27836	0136	Dallas	DB109491AA	iButton F50 w/Bum	300	77	0
DS1992	E7-F	DEC '01	28569	0201	Dallas	304746-1	iButton F50 w/Bum	300	77	0
DS29020	A7-3	JUN '01	27165	0158	Dallas	DX043531AEA	Cartridge	300	77	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1232	C2-L	JUL '01	27340	0105	ATP (Amkor, PI)	DK046225AB	SOIC	300	40	0
DS1232	C2-L	JUL '01	27340	0105	ATP (Amkor, PI)	DK046225AB	SOIC	1000	40	0
DS1232	C2-L	APR '01	26865	0105	OSEP	DE045054ABB	SOIC	300	40	1
DS1232	C2-L	APR '01	26865	0105	OSEP	DE045054ABB	SOIC	1000	39	0
DS1233	A5	APR '01	26872	0101	Fastech	DA048537AF	SOT223	700	40	10
DS1233	A5	APR '01	26872	0101	Fastech	DA048537AF	SOT223	1000	29	0
DS1233	A5	JUL '01	27353	0110	Carsem	DM048543AA	SOT223	700	40	0
DS1233	A5	JUL '01	27353	0110	Carsem	DM048543AA	SOT223	1000	26	0
DS1233	A5	OCT '01	28007	0128	Fastech	DA102602AC	SOT223	700	40	0
DS1233	A5	OCT '01	28007	0128	Fastech	DA102602AC	SOT223	1000	40	0
DS1267	A1	MAY '01	26980	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	300	35	0
DS1267	A1	MAY '01	26980	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	1000	35	0
DS1620	D1	JUN '01	27094	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	300	40	0
DS1620	D1	JUN '01	27094	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	1000	40	0
DS1620	D1	SEP '01	27860	0111	NSEB	DJ051232AAI	SOIC	300	40	0
DS1620	D1	SEP '01	27860	0111	NSEB	DJ051232AAI	SOIC	1000	40	0
DS1620	D1	DEC '01	28594	0112	CPS (ChipPac, China)	DH052443AAD	SOIC	300	40	0
DS1620	D1	DEC '01	28594	0112	CPS (ChipPac, China)	DH052443AAD	SOIC	1000	40	0
DS1803	A2	FEB '01	26611	0105	OSEP	DE047362AAB	SOIC	300	40	0
DS1803	A2	FEB '01	26611	0105	OSEP	DE047362AAB	SOIC	1000	34	0
DS1803	A2	MAY '01	26994	0115	Carsem	DM052456AC	SOIC	300	40	0
DS1803	A2	MAY '01	26994	0115	Carsem	DM052456AC	SOIC	1000	31	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1803	A2	AUG '01	27564	0119	OSEP	DE105519ACA	SOIC	300	40	0
DS1803	A2	AUG '01	27564	0119	OSEP	DE105519ACA	SOIC	1000	40	0
DS2108	B7	AUG '00	25859	0029	ATP (Amkor, PI)	DK016058AA	SOIC	300	40	0
DS2108	B7	AUG '00	25859	0029	ATP (Amkor, PI)	DK016058AA	SOIC	1000	40	0
DS2118M	B1	SEP '01	27875	0124	Carsem	DM106644AA	SSOP	300	80	0
DS2118M	B1	SEP '01	27875	0124	Carsem	DM106644AA	SSOP	1000	70	0
DS21352	A4	JUN '01	27347	0103	ATP (Amkor, PI)	DN033071AAA	LQFP	300	80	0
DS21352	A4	JUN '01	27347	0103	ATP (Amkor, PI)	DN033071AAA	LQFP	1000	79	0
DS2154	A2	JUN '01	27102	0107	Stats	DC040702AA-	LQFP	300	80	0
DS2154	A2	JUN '01	27102	0107	Stats	DC040702AA-	LQFP	1000	80	0
DS2154	A2	SEP '01	27842	0125	ATK (Amkor, K)	DN104641AA-	LQFP	300	80	0
DS2154	A2	SEP '01	27842	0125	ATK (Amkor, K)	DN104641AA-	LQFP	1000	80	0
DS2154	A2	DEC '01	28584	0126	ATP (Amkor, PI)	DK119150AAA	LQFP	300	72	0
DS2175	D1	APR '01	26884	0050	ATP (Amkor, PI)	DK036683AB	SOIC	300	40	0
DS2175	D1	APR '01	26884	0050	ATP (Amkor, PI)	DK036683AB	SOIC	1000	40	0
DS21Q43	A3-A	SEP '01	27881	0047	Stats	DC036714AAD	LQFP	300	77	0
DS21S07	C1-	FEB '01	26589	0047	Carsem	DM035532AF	TSSOP	300	40	0
DS21S07	C1-	FEB '01	26589	0047	Carsem	DM035532AF	TSSOP	1000	40	0
DS2401	C2	SEP '01	27885	0130	Fastech	DA033008AJ	TO92	300	40	0
DS2401	C2	SEP '01	27885	0130	Fastech	DA033008AJ	TO92	1000	40	0
DS2502	C4	APR '01	26917	0107	OSEP	DE041143AKA	TSOC	300	77	0
DS2502	C4	APR '01	26917	0107	OSEP	DE041143AKA	TSOC	1000	77	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS2502	C4	JUL '01	27375	0125	OSEP	DE052527ACA	TSOC	300	77	0
DS2502	C4	JUL '01	27375	0125	OSEP	DE052527ACA	TSOC	1000	77	0
DS5002	C5	JAN '01	26510	0047	ATK (Amkor, K)	DN028766AAD	MQFP	300	40	0
DS5002	C5	JAN '01	26510	0047	ATK (Amkor, K)	DN028766AAD	MQFP	1000	40	0
DS5002	C5	APR '01	26902	0112	ATK (Amkor, K)	DN030363AAA	MQFP	300	40	0
DS5002	C5	APR '01	26902	0112	ATK (Amkor, K)	DN030363AAA	MQFP	1000	40	0
DS5002	C6	JUL '01	27365	0122	ATK (Amkor, K)	DN042297AAA	MQFP	300	40	0
DS5002	C6	JUL '01	27365	0122	ATK (Amkor, K)	DN042297AAA	MQFP	1000	40	0
DS80C320	C5	APR '01	26895	0111	CPS (ChipPac, China)	DH040746AA	PDIP	300	40	0
DS80C320	C5	APR '01	26895	0111	CPS (ChipPac, China)	DH040746AA	PDIP	1000	40	0
DS80CH11	A4	MAR '01	26787	0103	ATK (Amkor, K)	DN029182AAA	LQFP	300	70	0
DS80CH11	A4	MAR '01	26787	0103	ATK (Amkor, K)	DN029182AAA	LQFP	1000	70	0
DS80CH11	A4	JUN '01	27108	0108	ATK (Amkor, K)	DN034351AA	LQFP	300	70	0
DS80CH11	A4	SEP '01	27868	0110	Stats	DC037148AA	LQFP	300	70	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: 0C TO 70C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	NOV '01	28565	0151 Dallas	304797	Module w/Hi Densit	300	77	0
DS1643	C1	NOV '01	28565	0151 Dallas	304797	Module w/Hi Densit	1000	77	0
DS3816	A-C	& DS3801	26054	0041 Dallas	120701	BGA Module, 2 Sid	300	33	0
DS3816	A-C	& DS3801	26054	0041 Dallas	120701	BGA Module, 2 Sid	1000	28	0
DS3816	A-C	& DS3801	26054	0041 Dallas	120701	BGA Module, 2 Sid	2000	25	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 150C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1620	D1	MAR '01	26781	0106	CPS (ChipPac, China)	DH045040AA	SOIC	336	50	0
DS1620	D1	MAR '01	26781	0106	CPS (ChipPac, China)	DH045040AA	SOIC	1000	50	0
DS1620	D1	JUN '01	27097	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	336	50	0
DS1620	D1	JUN '01	27097	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	1000	50	0
DS1620	D1	SEP '01	27863	0111	NSEB	DJ051232AAI	SOIC	336	50	0
DS1620	D1	SEP '01	27863	0111	NSEB	DJ051232AAI	SOIC	1000	50	0
DS1620	D1	DEC '01	28597	0112	CPS (ChipPac, China)	DH052443AAD	SOIC	336	50	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 70 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1643	C1	NOV '01	28564	0151 Dallas	304797	Module w/Hi Densit	336	77	0
DS1643	C1	NOV '01	28564	0151 Dallas	304797	Module w/Hi Densit	1000	77	0
DS1644	B2	& DS9034	26627	0051 Fastech	300700	Power Cap	336	71	1
DS1644	B2	& DS9034	26627	0051 Fastech	300700	Power Cap	1000	69	0
DS1992	E7-F	SEP '01	27835	0136 Dallas	DB109491AA	iButton F50 w/Bum	336	77	0
DS1992	E7-F	SEP '01	27835	0136 Dallas	DB109491AA	iButton F50 w/Bum	1000	77	0
DS1992	E7-F	DEC '01	28568	0201 Dallas	304746-1	iButton F50 w/Bum	336	77	0
DS1992	E7-F	DEC '01	28568	0201 Dallas	304746-1	iButton F50 w/Bum	1000	77	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 85 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	A1-Y	JUL '01	27333	0119 Fastech	302244	Module w/SMT	48	200	1
DS1230	A1-Y	JAN '02	28620	0201 Fastech	304930	Module w/SMT	48	200	0
DS29020	A7-3	JUN '01	27164	0158 Dallas	DX043531AEA	Cartridge	336	77	0
DS3816	A-C	& DS3801	26053	0041 Dallas	120701	BGA Module, 2 Sid	336	33	0
DS3816	A-C	& DS3801	26053	0041 Dallas	120701	BGA Module, 2 Sid	1000	30	1
DS3816	A-C	& DS3801	26053	0041 Dallas	120701	BGA Module, 2 Sid	2000	29	0

RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: JESD22-B102

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1230	A1-Y	JUL '01	27331	0119	Fastech	302244	Module w/SMT	3	0
DS1230	A1-Y	JAN '02	28618	0201	Fastech	304930	Module w/SMT	3	0
DS12887	A2-	JUL '01	27356	0121	Fastech	302296	Module w/Bent Fra	3	0
DS12887	A2-	OCT '01	28010	0137	Fastech	303363	Module w/Bent Fra	3	0
DS12887	A2-	JAN '02	28605	0203	Dallas	305911	Module w/Bent Fra	3	0

RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: MIL-STD-883-2003

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS12887	A2-	JAN '01	26448	0043	Fastech	300511	Module w/Bent Fra	3	0
DS12887	A2-	APR '01	26875	0102	Fastech	301097	Module w/Bent Fra	3	0
DS1643	C1	NOV '01	28562	0151	Dallas	304797	Module w/Hi Densit	3	0

RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1232	C2-L	JUL '01	27338	0105	ATP (Amkor, PI)	DK046225AB	SOIC	4	0
DS1232	C2-L	APR '01	26863	0105	OSEP	DE045054ABB	SOIC	4	0
DS1620	D1	MAR '01	26775	0106	CPS (ChipPac, China)	DH045040AA	SOIC	4	0
DS1620	D1	JUN '01	27092	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	4	0
DS1620	D1	SEP '01	27858	0111	NSEB	DJ051232AAI	SOIC	4	0
DS1803	A2	FEB '01	26608	0105	OSEP	DE047362AAB	SOIC	4	0
DS2108	B7	AUG '00	25856	0029	ATP (Amkor, PI)	DK016058AA	SOIC	4	0
DS2118M	B1	SEP '01	27873	0124	Carsem	DM106644AA	SSOP	4	4
DS21352	A4	JUN '01	27345	0103	ATP (Amkor, PI)	DN033071AAA	LQFP	4	0
DS2154	A2	JUN '01	27100	0107	Stats	DC040702AA-	LQFP	4	0
DS2154	A2	SEP '01	27840	0125	ATK (Amkor, K)	DN104641AA-	LQFP	4	0
DS2154	A2	DEC '01	28582	0126	ATP (Amkor, PI)	DK119150AAA	LQFP	4	0
DS21S07	C1-	FEB '01	26586	0047	Carsem	DM035532AF	TSSOP	4	0
DS2502	C4	APR '01	26916	0107	OSEP	DE041143AKA	TSOC	4	0
DS2502	C4	JUL '01	27374	0125	OSEP	DE052527ACA	TSOC	4	0
DS5002	C5	JAN '01	26507	0047	ATK (Amkor, K)	DN028766AAD	MQFP	4	0
DS5002	C5	APR '01	26900	0112	ATK (Amkor, K)	DN030363AAA	MQFP	4	0
DS5002	C6	JUL '01	27363	0122	ATK (Amkor, K)	DN042297AAA	MQFP	4	0
DS80CH11	A4	MAR '01	26784	0103	ATK (Amkor, K)	DN029182AAA	LQFP	4	0
DS80CH11	A4	JUN '01	27106	0108	ATK (Amkor, K)	DN034351AA	LQFP	4	0
DS80CH11	A4	SEP '01	27866	0110	Stats	DC037148AA	LQFP	4	0
DS80CH11	A4	DEC '01	28600	0113	ATK (Amkor, K)	DN036754AA	LQFP	4	0

RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: JESD22-B100

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS1230	A1-Y	JUL '01	27332	0119 Fastech	302244	Module w/SMT	6 0
DS12887	A2-	JUL '01	27357	0121 Fastech	302296	Module w/Bent Fra	6 0

RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: MIL-STD-883-2016

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS12887	A2-	JAN '01	26449	0043 Fastech	300511	Module w/Bent Fra	6 0
DS12887	A2-	APR '01	26876	0102 Fastech	301097	Module w/Bent Fra	6 0

RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 60C/90% R.H.

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1230	A1-Y	JUL '01	27335	0119	Fastech	302244	Module w/SMT	288	100	0
DS1230	A1-Y	JUL '01	27335	0119	Fastech	302244	Module w/SMT	960	100	0
DS1230	A1-Y	JAN '02	28622	0201	Fastech	304930	Module w/SMT	288	100	1
DS1644	B2	& DS9034	26629	0051	Fastech	300700	Power Cap	288	77	0
DS1644	B2	& DS9034	26629	0051	Fastech	300700	Power Cap	960	72	0
DS1992	E7-F	SEP '01	27837	0136	Dallas	DB109491AA	iButton F50 w/Bum	288	77	0
DS1992	E7-F	SEP '01	27837	0136	Dallas	DB109491AA	iButton F50 w/Bum	960	77	0
DS1992	E7-F	DEC '01	28570	0201	Dallas	304746-1	iButton F50 w/Bum	288	77	0
DS3816	A-C	& DS3801	26055	0041	Dallas	120701	BGA Module, 2 Sid	288	33	2

RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 85 C/85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS29020	A7-3	JUN '01	27166	0158	Dallas	DX043531AEA	Cartridge	274	77	0

RELIABILITY MONITOR

STRESS: INFANT LIFE

CONDITIONS: 85 C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	JAN '01	26450	0043 Fastech	300511	Module w/Bent Fra	48	200	0
DS12887	A2-	APR '01	26877	0102 Fastech	301097	Module w/Bent Fra	48	200	0
DS12887	A2-	JUL '01	27358	0121 Fastech	302296	Module w/Bent Fra	48	200	0
DS12887	A2-	OCT '01	28012	0137 Fastech	303363	Module w/Bent Fra	48	200	0

RELIABILITY MONITOR

STRESS: HAST, NO BIAS

CONDITIONS: 130C, 85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS21352	A4	JUN '01	27348	0103 ATP (Amkor, PI)	DN033071AAA	LQFP	200	62	0
DS2154	A2	JUN '01	27103	0107 Stats	DC040702AA-	LQFP	200	76	0
DS2154	A2	SEP '01	27843	0125 ATK (Amkor, K)	DN104641AA-	LQFP	200	77	0
DS2154	A2	DEC '01	28585	0126 ATP (Amkor, PI)	DK119150AAA	LQFP	200	72	0
DS21Q43	A3-A	SEP '01	27883	0047 Stats	DC036714AAD	LQFP	100	40	0
DS80CH11	A4	MAR '01	26789	0103 ATK (Amkor, K)	DN029182AAA	LQFP	100	40	0
DS80CH11	A4	JUN '01	27110	0108 ATK (Amkor, K)	DN034351AA	LQFP	100	40	1
DS80CH11	A4	SEP '01	27870	0110 Stats	DC037148AA	LQFP	100	40	0

RELIABILITY MONITOR

STRESS: HAST

CONDITIONS: 130C, 85%R.H.,5.5V

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1232	C2-L	JUL '01	27341	0105 ATP (Amkor, PI)	DK046225AB	SOIC	100	77	1
DS1232	C2-L	APR '01	26866	0105 OSEP	DE045054ABB	SOIC	88	77	0
DS1233	A5	APR '01	26873	0101 Fastech	DA048537AF	SOT223	100	77	0
DS1233	A5	JUL '01	27354	0110 Carsem	DM048543AA	SOT223	100	77	0
DS1233	A5	OCT '01	28008	0128 Fastech	DA102602AC	SOT223	100	77	0
DS2401	C2	SEP '01	27886	0130 Fastech	DA033008AJ	TO92	100	77	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1644	B2	& DS9034	26625	0051	Fastech	300700	Power Cap	2	225	0
DS3816	A-C	& DS3801	26051	0041	Dallas	120701	BGA Module, 2 Sid	2	99	0
DS5002	C6	JUL '01	27362	0122	ATK (Amkor, K)	DN042297AAA	MQFP	3	206	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1232	C2-L	JUL '01	27337	0105	ATP (Amkor, PI)	DK046225AB	SOIC	3	241	0
DS1232	C2-L	APR '01	26862	0105	OSEP	DE045054ABB	SOIC	3	238	0
DS1233	A5	APR '01	26869	0101	Fastech	DA048537AF	SOT223	3	238	0
DS1233	A5	JUL '01	27350	0110	Carsem	DM048543AA	SOT223	3	241	0
DS1233	A5	OCT '01	28004	0128	Fastech	DA102602AC	SOT223	3	241	1
DS1267	A1	MAY '01	26977	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	3	238	0
DS1620	D1	MAR '01	26774	0106	CPS (ChipPac, China)	DH045040AA	SOIC	3	241	0
DS1620	D1	JUN '01	27091	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	3	241	0
DS1620	D1	SEP '01	27857	0111	NSEB	DJ051232AAI	SOIC	3	244	0
DS1620	D1	DEC '01	28591	0112	CPS (ChipPac, China)	DH052443AAD	SOIC	3	244	0
DS1803	A2	FEB '01	26607	0105	OSEP	DE047362AAB	SOIC	3	238	0
DS1803	A2	MAY '01	26991	0115	Carsem	DM052456AC	SOIC	3	238	0
DS1803	A2	AUG '01	27561	0119	OSEP	DE105519ACA	SOIC	3	241	0
DS2108	B7	AUG '00	25855	0029	ATP (Amkor, PI)	DK016058AA	SOIC	3	238	0
DS2118M	B1	SEP '01	27872	0124	Carsem	DM106644AA	SSOP	3	241	1
DS21352	A4	JUN '01	27344	0103	ATP (Amkor, PI)	DN033071AAA	LQFP	3	238	5
DS2154	A2	JUN '01	27099	0107	Stats	DC040702AA-	LQFP	3	238	0
DS2154	A2	SEP '01	27839	0125	ATK (Amkor, K)	DN104641AA-	LQFP	3	241	0
DS2154	A2	DEC '01	28581	0126	ATP (Amkor, PI)	DK119150AAA	LQFP	3	238	1
DS2175	D1	APR '01	26881	0050	ATP (Amkor, PI)	DK036683AB	SOIC	3	238	0
DS21Q43	A3-A	SEP '01	27878	0047	Stats	DC036714AAD	LQFP	3	241	0
DS21S07	C1-	FEB '01	26585	0047	Carsem	DM035532AF	TSSOP	3	238	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS2502	C4	APR '01	26915	0107	OSEP	DE041143AKA	TSOC	3	151	0
DS2502	C4	JUL '01	27373	0125	OSEP	DE052527ACA	TSOC	3	151	0
DS80CH11	A4	JUN '01	27105	0108	ATK (Amkor, K)	DN034351AA	LQFP	3	239	0
DS80CH11	A4	SEP '01	27865	0110	Stats	DC037148AA	LQFP	3	242	0
DS80CH11	A4	DEC '01	28599	0113	ATK (Amkor, K)	DN036754AA	LQFP	3	244	1

RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1267	A1	MAY '01	26981	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	274	75	0
DS1267	A1	MAY '01	26981	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	959	75	0
DS12887	A2-	JAN '01	26452	0043	Fastech	300511	Module w/Bent Fra	274	100	0
DS12887	A2-	JAN '01	26452	0043	Fastech	300511	Module w/Bent Fra	959	96	0
DS12887	A2-	APR '01	26879	0102	Fastech	301097	Module w/Bent Fra	274	100	1
DS12887	A2-	APR '01	26879	0102	Fastech	301097	Module w/Bent Fra	959	99	0
DS12887	A2-	JUL '01	27360	0121	Fastech	302296	Module w/Bent Fra	274	100	0
DS12887	A2-	JUL '01	27360	0121	Fastech	302296	Module w/Bent Fra	959	100	0
DS12887	A2-	OCT '01	28014	0137	Fastech	303363	Module w/Bent Fra	274	99	0
DS12887	A2-	OCT '01	28014	0137	Fastech	303363	Module w/Bent Fra	959	99	0
DS12887	A2-	JAN '02	28608	0203	Dallas	305911	Module w/Bent Fra	274	100	0
DS12887	A2-	JAN '02	28608	0203	Dallas	305911	Module w/Bent Fra	959	100	11
DS1620	D1	JUN '01	27095	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	274	70	1
DS1620	D1	JUN '01	27095	0109	CPS (ChipPac, China)	DH046190AAI	SOIC	959	69	0
DS1620	D1	SEP '01	27861	0111	NSEB	DJ051232AAI	SOIC	274	70	0
DS1620	D1	SEP '01	27861	0111	NSEB	DJ051232AAI	SOIC	959	70	0
DS1620	D1	DEC '01	28595	0112	CPS (ChipPac, China)	DH052443AAD	SOIC	274	70	0
DS1803	A2	FEB '01	26612	0105	OSEP	DE047362AAB	SOIC	274	77	0
DS1803	A2	FEB '01	26612	0105	OSEP	DE047362AAB	SOIC	959	66	3
DS1803	A2	MAY '01	26995	0115	Carsem	DM052456AC	SOIC	274	77	0
DS1803	A2	MAY '01	26995	0115	Carsem	DM052456AC	SOIC	959	77	0
DS1803	A2	AUG '01	27565	0119	OSEP	DE105519ACA	SOIC	274	77	0

RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1803	A2	AUG '01	27565	0119	OSEP	DE105519ACA	SOIC	959	77	0
DS2108	B7	AUG '00	25860	0029	ATP (Amkor, PI)	DK016058AA	SOIC	274	77	3
DS2108	B7	AUG '00	25860	0029	ATP (Amkor, PI)	DK016058AA	SOIC	959	74	0
DS2175	D1	APR '01	26885	0050	ATP (Amkor, PI)	DK036683AB	SOIC	274	77	0
DS21S07	C1-	FEB '01	26590	0047	Carsem	DM035532AF	TSSOP	274	77	0
DS21S07	C1-	FEB '01	26590	0047	Carsem	DM035532AF	TSSOP	959	77	0
DS5002	C5	JAN '01	26511	0047	ATK (Amkor, K)	DN028766AAD	MQFP	274	42	0
DS5002	C5	JAN '01	26511	0047	ATK (Amkor, K)	DN028766AAD	MQFP	959	41	0
DS5002	C5	APR '01	26903	0112	ATK (Amkor, K)	DN030363AAA	MQFP	274	42	0
DS5002	C5	APR '01	26903	0112	ATK (Amkor, K)	DN030363AAA	MQFP	959	42	0
DS5002	C6	JUL '01	27366	0122	ATK (Amkor, K)	DN042297AAA	MQFP	274	42	0
DS5002	C6	JUL '01	27366	0122	ATK (Amkor, K)	DN042297AAA	MQFP	959	41	0
DS80C320	C5	APR '01	26896	0111	CPS (ChipPac, China)	DH040746AA	PDIP	274	77	0
DS80C320	C5	APR '01	26896	0111	CPS (ChipPac, China)	DH040746AA	PDIP	959	77	0
DS80CH11	A4	MAR '01	26788	0103	ATK (Amkor, K)	DN029182AAA	LQFP	274	48	0
DS80CH11	A4	MAR '01	26788	0103	ATK (Amkor, K)	DN029182AAA	LQFP	959	45	0
DS80CH11	A4	JUN '01	27109	0108	ATK (Amkor, K)	DN034351AA	LQFP	274	46	1
DS80CH11	A4	SEP '01	27869	0110	Stats	DC037148AA	LQFP	274	42	0

RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C, 2 ATM STEAM, UNBIASED

PRODUCT	REV	MONITOR		DATE	ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO		CODE	FACILITY			POINT	QTY	FAIL
DS1232	C2-L	JUL '01	27342	0105	ATP (Amkor, PI)	DK046225AB	SOIC	96	39	0	
DS1232	C2-L	APR '01	26867	0105	OSEP	DE045054ABB	SOIC	96	40	0	
DS1233	A5	APR '01	26874	0101	Fastech	DA048537AF	SOT223	96	40	0	
DS1233	A5	JUL '01	27355	0110	Carsem	DM048543AA	SOT223	96	40	0	
DS1233	A5	OCT '01	28009	0128	Fastech	DA102602AC	SOT223	96	40	0	
DS1267	A1	MAY '01	26982	0104	ATP (Amkor, PI)	DK043419AAB	TSSOP	96	34	0	
DS1803	A2	FEB '01	26613	0105	OSEP	DE047362AAB	SOIC	96	30	0	
DS1803	A2	MAY '01	26996	0115	Carsem	DM052456AC	SOIC	96	37	0	
DS1803	A2	AUG '01	27566	0119	OSEP	DE105519ACA	SOIC	96	40	0	
DS2108	B7	AUG '00	25861	0029	ATP (Amkor, PI)	DK016058AA	SOIC	96	33	0	
DS2118M	B1	SEP '01	27876	0124	Carsem	DM106644AA	SSOP	96	76	0	
DS2175	D1	APR '01	26886	0050	ATP (Amkor, PI)	DK036683AB	SOIC	96	40	0	
DS21S07	C1-	FEB '01	26591	0047	Carsem	DM035532AF	TSSOP	96	36	0	
DS2401	C2	SEP '01	27887	0130	Fastech	DA033008AJ	TO92	96	40	0	
DS2502	C4	APR '01	26918	0107	OSEP	DE041143AKA	TSOC	96	70	0	
DS2502	C4	JUL '01	27376	0125	OSEP	DE052527ACA	TSOC	96	70	0	
DS5002	C5	JAN '01	26512	0047	ATK (Amkor, K)	DN028766AAD	MQFP	96	37	0	
DS5002	C5	APR '01	26904	0112	ATK (Amkor, K)	DN030363AAA	MQFP	96	39	0	
DS5002	C6	JUL '01	27367	0122	ATK (Amkor, K)	DN042297AAA	MQFP	96	40	0	
DS80C320	C5	APR '01	26897	0111	CPS (ChipPac, China)	DH040746AA	PDIP	96	40	0	

RELIABILITY MONITOR

STRESS: 0 HR TEST

CONDITIONS: Connect Cap & Base

PRODUCT	REV	MONITOR	DATE	JOB NO	ASSEMBLY	LOT NO.	PACKAGE	READ	POINT	QTY	FAIL
DS1644	B2	& DS9034	26626	0051	Fastech	300700	Power Cap	2	230	5	